CLAIMS

What is claimed:

1. A method of producing a device for securing conductors, the method comprising the steps of:

shaping a connector device to include bendable flaps for securing a conductor; and

forming the connector device to include an external surface that is eventually affixed to a substantially complementary shaped surface, at least a portion of the conductor secured in the connector device also being affixed to the substantially complementary shaped surface, the conductor being bent near the connector device in a manner so that at least a portion of the conductor and the external surface of the connector device lie in a common contour.

2. A method as in claim 1, wherein the external surface is substantially flat and at least a portion of the conductor and external surface lie in a common plane.

3. A method as in claim 1 further comprising the steps of:

providing a strip of flat metal; and

bending the strip of flat metal to form the bendable flaps of a connector device, a portion of the strip of flat metal forming the external surface that is eventually attached to the complementary surface.

4. A method as in claim 1, wherein the connector device includes two or more sets of bendable flaps.

5. A method as in claim 1, wherein the connector device is electrically conductive.

6. A method as in claim 1, wherein the external surface of the connector device is soldered to a complementary shaped surface.

7. A method as in claim 1, wherein a lead is crimped to the conductor via the connector device.

8. A method as in claim 1 further comprising the step of:

shaping the connector device to include a tongue for attaching a lead wire.

9. A method as in claim 8, wherein a lead wire can be removably attached to the tongue.

10. A method as in claim 9, wherein the tongue is disposed above a corresponding surface to which the connector device is attached.

11. A method of attaching conductors comprising the steps of:

providing a connector device having bendable flaps for securing a conductor strip when the flaps are crimped, the connector device including an external surface for attachment to a substantially complementary shaped surface;

crimping at least a portion of the conductor strip to the connector device by bending the flaps; and

attaching the connector device and at least a portion of the conductor strip to the substantially complementary surface, the conductor being bent near the connector device in a manner so that at least a portion of the conductor and the external surface of the connector device lie in a common contour.

12. A method as in claim 11, wherein the step of crimping further comprises:

bending the set of flaps of the connector device inwards towards each other to secure a lead wire to the conductor strip.

13. A method as in claim 11, wherein the connector device is crimped around a lengthwise portion of the conductor strip to attach a distal end of a lead wire to the conductor strip.

14. A method as in claim 11, wherein the connector device is electrically conductive.

15. A method as in claim 11 further comprising the steps of:

disposing a lead wire above the conductor strip and thereafter crimping the flaps of the connector device to attach the lead wire to the conductor strip; and

bending a portion of the conductor strip extending through the connector device such that at least a portion of the conductor strip lies in a common plane with the external surface of the connector device.

16. A method as in claim 15, wherein the step of bending a portion of the conductor strip includes applying a force on a portion of the conductor strip extending beyond an edge of the connector device.

17. A method as in claim 11, wherein the conductor strip includes a braided wire.

18. A method as in claim 11, wherein the conductor strip comprises a braided wire with a solder core.

19. A method as in claim 11 further comprising the steps of:

contacting the external surface of the connector device to the complementary shaped surface; and

applying heat to the connector device for soldering the connector device to the complementary shaped surface.

20. A method as in claim 19, wherein the complementary shaped surface is a layer of glass.

21. A method as in claim 11 further comprising the step of:

applying heat to the conductor strip and connector device for attachment to glass.

22. A method as in claim 11 further comprising the step of:

bending the flaps of the connector device to crimp a lead wire to a braid of wire.

23. A method as in claim 22 further comprising the steps of:

heating the braid of wire; and

applying solder to the braid of wire.

24. A method as in claim 11 further comprising the step of:

attaching individual solder masses along the conductor strip.

25. A method of forming an assembly comprising:

providing a conductor;

securing a connector device to the conductor by crimping bendable flaps extending from the connector device, the connector device having an external surface; and

bending the conductor near the connector device in a manner so that at least a portion of the conductor and the external surface of the connector device lie in a common contour for attaching to a surface.